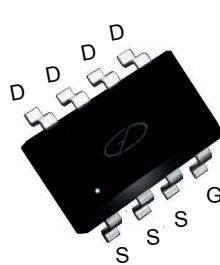
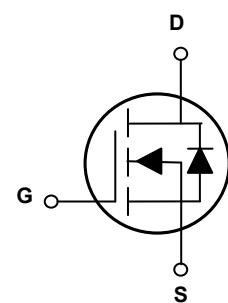


Main Product Characteristics

BV _{DSS}	150V
R _{DS(ON)}	68mΩ (max)
I _D	4.6A



SOP-8



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSGQ5R515 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	150	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	4.6	A
Drain Current-Continuous ($T_A=100^\circ\text{C}$)		3.3	
Pulsed Drain Current	I _{DM}	18.4	A
Maximum Power Dissipation	P _D	3	W
Single Pulse Avalanche Energy ¹	E _{AS}	30	mJ
Thermal Resistance, Junction-to-Ambient ²	R _{θJA}	42	°C/W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
On / Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	150	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DS}}^{\text{SS}}$	$V_{\text{DS}}=150\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	1.3	1.9	2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_D=2\text{A}$	-	59	68	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=2\text{A}$	-	72	95	
Forward Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=2\text{A}$	-	7	-	S
Dynamic and Switching Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}}=75\text{V}, V_{\text{GS}}=0\text{V}, f=1.0\text{MHz}$	-	799	-	pF
Output Capacitance	C_{oss}		-	74.4	-	
Reverse Transfer Capacitance	C_{rss}		-	11.1	-	
Turn-on Delay Time ³	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=75\text{V}, R_L=7.5\Omega, V_{\text{GS}}=10\text{V}, R_G=3\Omega$	-	10.5	-	nS
Turn-on Rise Time ³	t_r		-	6	-	
Turn-Off Delay Time ³	$t_{\text{d}(\text{off})}$		-	14.5	-	
Turn-Off Fall Time ³	t_f		-	3.5	-	
Total Gate Charge ³	Q_g	$V_{\text{DS}}=75\text{V}, I_D=2\text{A}, V_{\text{GS}}=10\text{V}$	-	15	-	nC
Gate-Source Charge ³	Q_{gs}		-	4.5	-	
Gate-Drain Charge ³	Q_{gd}		-	3	-	
Drain-Source Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_S=2\text{A}$	-	-	1.2	V
Diode Forward Current	I_S	-	-	-	4.6	A
Reverse Recovery Time	T_{rr}	$T_J=25^\circ\text{C}, I_F=I_S$ $dI/dt=100\text{A}/\mu\text{s}$	-	29.5	-	nS
Reverse Recovery Charge	Q_{rr}		-	132	-	nC

Notes:

1. EAS condition: $T_J=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_G=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$.
2. The value of R_{\thetaJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.
3. Guaranteed by design, not subject to production.
4. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

Typical Electrical and Thermal Characteristic Curves

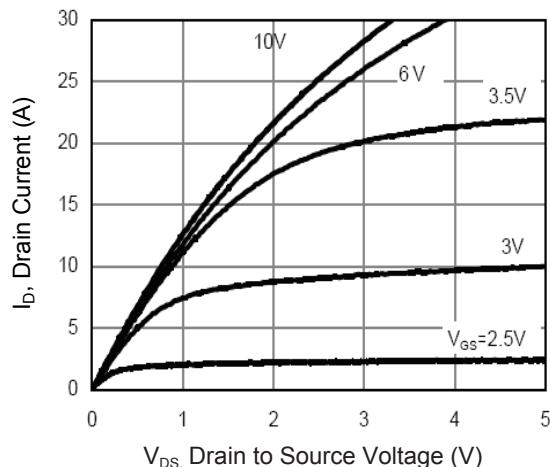


Figure 1. Output Characteristics

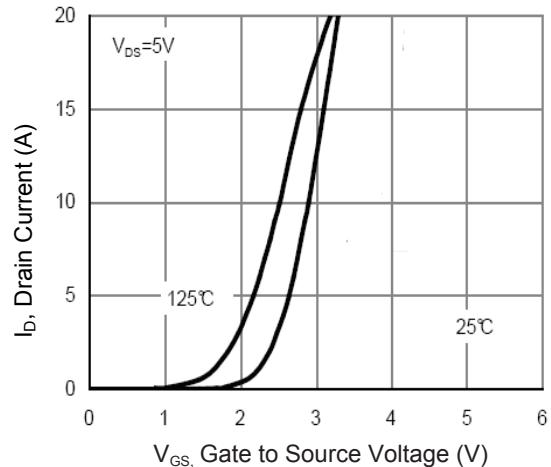


Figure 2. Transfer Characteristics

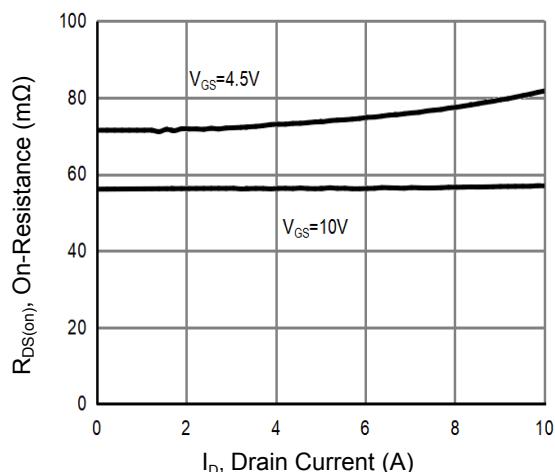


Figure 3. $R_{DS(on)}$ vs. Drain Current

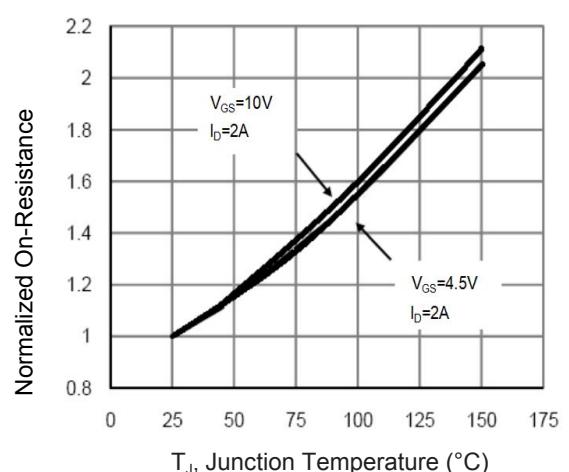


Figure 4. $R_{DS(on)}$ vs. Junction Temperature

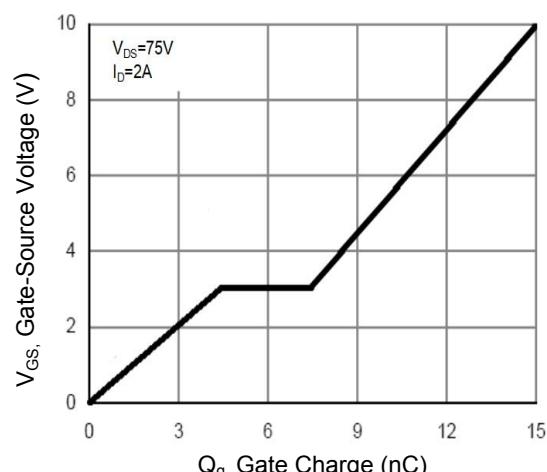


Figure 5. Gate Charge

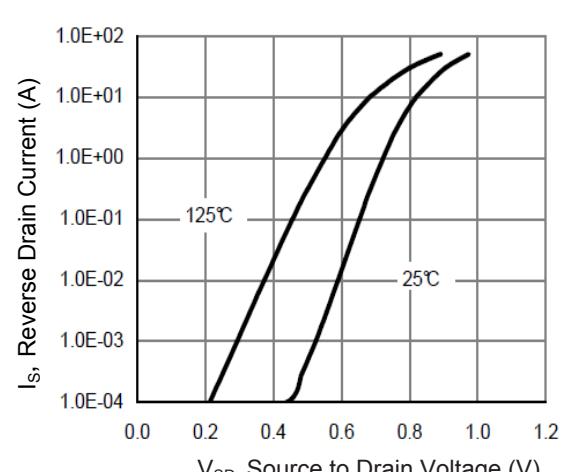


Figure 6. Source-Drain Diode Forward Voltage

Typical Electrical and Thermal Characteristic Curves

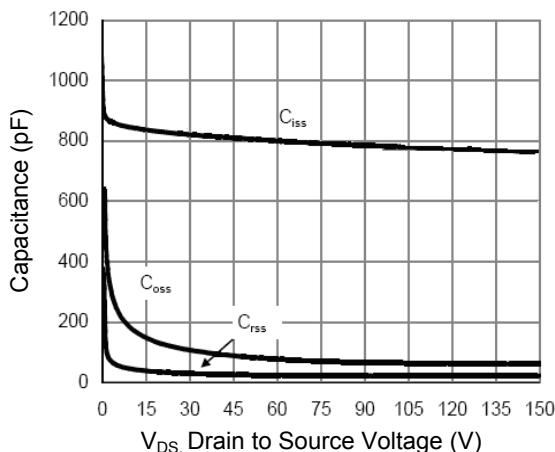


Figure 7. Capacitance vs. V_{DS}

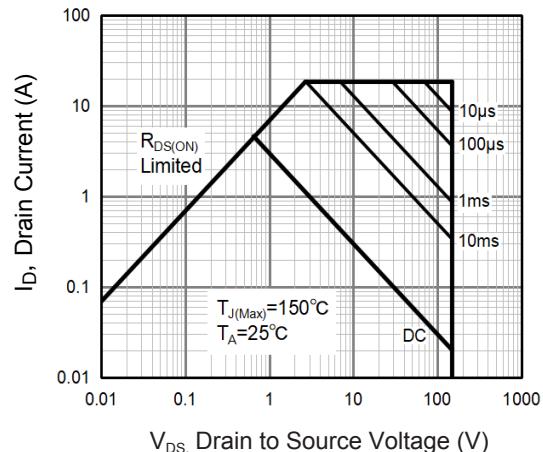


Figure 8. Safe Operating Area

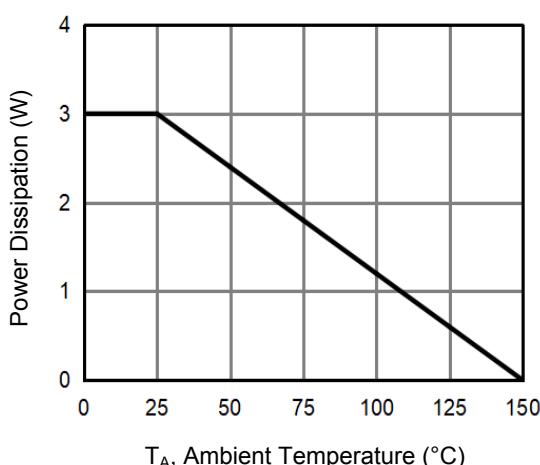


Figure 9. Power De-rating

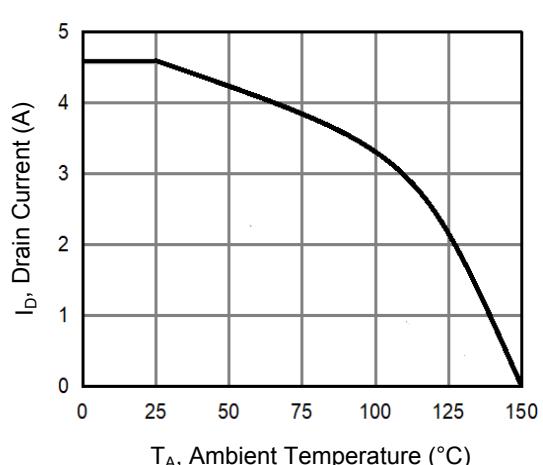


Figure 10. Current De-rating

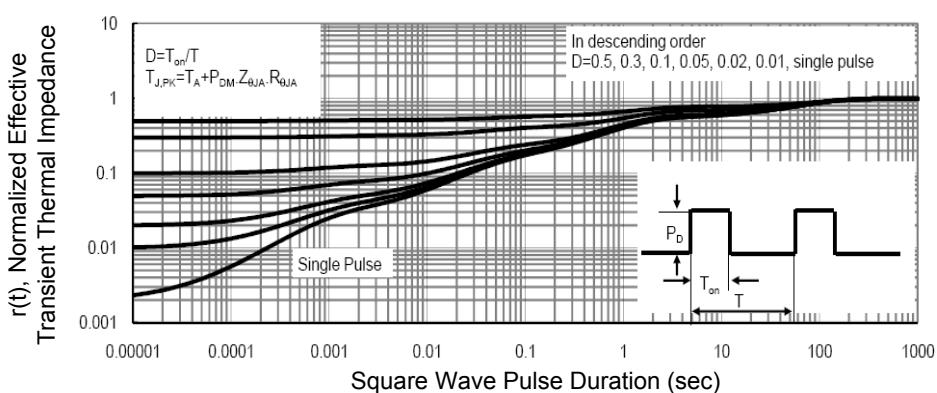
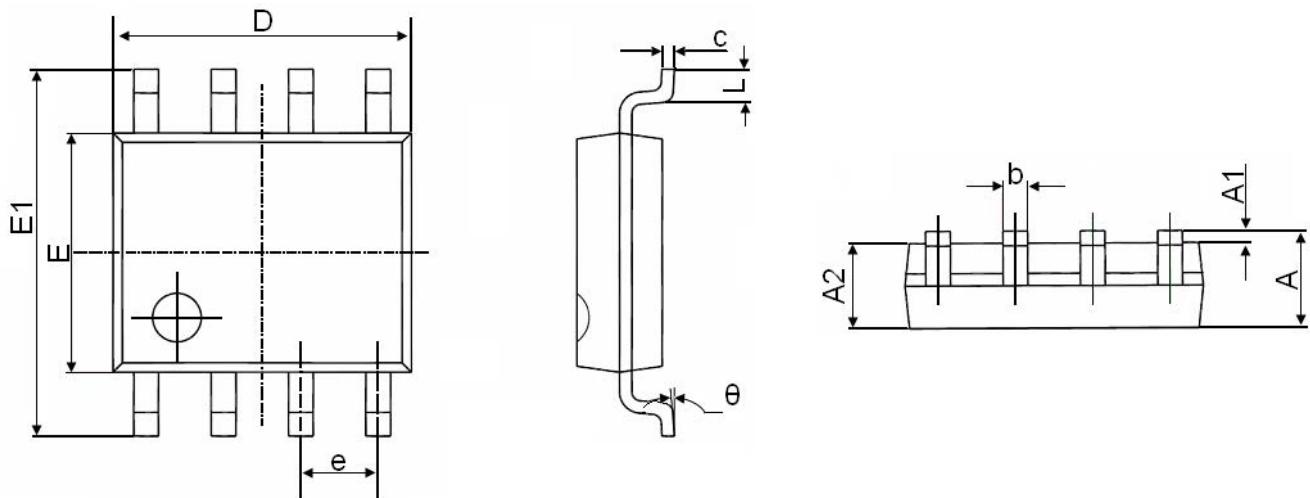


Figure 11. Normalized Maximum Transient Thermal Impedance

Package Outline Dimensions (SOP-8)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Order Information

Device	Package	Carrier	Quantity	HSF Status
GSGQ5R515	SOP-8	Tape & Reel	4,000pcs /Reel	RoHS Compliant